### Remarks

#### I. Status of Claims

The claims have been amended to clarify the inventive subject matter. Specifically, the subject matter of claim 9 has been incorporated into claim 1. No new matter has been added.

### II. Prior Art Rejections

The examiner rejected claim 1 under 35 U.S.C. 102(b) and claims 2-7 under 35 U.S.C. 103(a) based on primarily Hosoi (JP 61-058259). Although applicants do not agree with this rejection, it is rendered moot by the incorporation of the allowable subject matter of claim 9 into claim 1 as discussed below.

## III. Allowable Subject Matter

Applicants gratefully acknowledge the examiner's finding of allowable subject matter in claim 9. This subject matter has been incorporated into claim 1, rendering it allowable along with the claims that depend from it.

In addition to the examiner's reasons for the indication of allowable subject matter, applicants would like to add that, unlike the present application, Hosoi fails to recognize the detrimental magnetic effects resulting from stoichiometric and thickness variations in the nickel layer. Rather, Hosoi was concerned with the corrosiveness of nickel and the detrimental effects nickel "rust" has on the electrical conductivity between the metalized layer 3 and the wiring conductor 8. Accordingly, Hosoi does not discourage the use of nickel anywhere in the packaging except at this electrical interface. To the contrary, Hosoi indicates that the palladium needs to be applied "only on the bottom surface portion opposing wiring conductor 8 of external electric wiring substrate 7." (P. 3, right column, 2<sup>nd</sup> paragraph). Furthermore, when describing the attachment of the cover 2 on the substrate 1, Hosoi indicates that a sealing material such as glass or resin may be used. (Id. at 3<sup>rd</sup> paragraph.) There is no disclosure of using a palladium layer too for this interface. This is not surprising, since, according to Hosoi, palladium is used to enhance electrical conductively, which is irrelevant to the cover interface.

U.S. Patent Application No. 10/797,457 Attorney Docket No. 18130 US Page 6

# IV. Supplemental IDS

Applicants are submitting concurrently herewith a supplement IDS which includes a translated copy of Hosoi (JP 61-058259). The examiner is encouraged to scrutinize this reference in light of applicants' remarks above.

An early and favorable response is respectfully submitted.

Respectfully submitted,

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